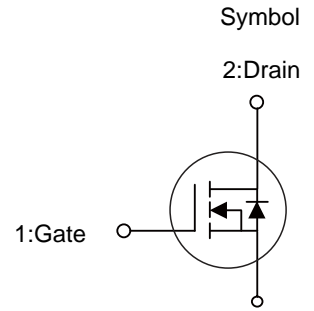


■ PRODUCT CHARACTERISTICS

V_{DSS}	30V
$R_{DS(ON) Typ} (@V_{GS}=10V)$	9m Ω
$R_{DS(ON) Typ} (@V_{GS}=4.5V)$	14m Ω
I_D	20A



■ APPLICATIONS

- * Electronic lamp ballasts based on half bridge
- * Load Switching, Quick/Wireless Charge.
- * Motor Driving

■ FEATURE

- * Low Gate Charge
- * Pb-Free Lead Plating



TO-252

■ ORDER INFORMATION

Order Codes		Package	Packing
Halogen-Free	Halogen		
N/A	MOT20N03BD	TO-252	2500 pieces/Reel

■ ABSOLUTE MAXIMUM RATINGS ($T_A=25^{\circ}C$, unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V_{DSS}	30	V
Gate-Source Voltage	V_{GSS}	± 20	V
Drain Current Continuous ($@V_{GS}=10V, T_A=25^{\circ}C$)	I_D	20	A
Drain Current Continuous ($@V_{GS}=10V, T_A=100^{\circ}C$)	I_D	14.1	A
Drain Current Pulsed	I_{DM}	80	A
Avalanche Energy *	E_{AS}	49	mJ
Power Dissipation	P_D	65	W
Junction Temperature	T_J	+150	$^{\circ}C$
Storage Temperature	T_{STG}	-55~ +150	$^{\circ}C$

■ THERMAL CHARACTERISTICS

Parameter	Symbol	Typ	Unit
Junction to Case	R_{thJC}	1.92	$^{\circ}C/W$

Note: * EAS condition: $T_J=25^{\circ}C, V_{DS}=20V, V_G=10V, L=0.5mH, R_g=25\Omega$

■ ELECTRICAL CHARACTERISTICS ($T_C=25^{\circ}\text{C}$, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Off characteristics						
Drain to Source Breakdown Voltage	V_{DSS}	$V_{GS}=0\text{V}, I_D=250\mu\text{A}$	30	-	-	V
Drain to Source Leakage Current	I_{DSS}	$V_{DS}=30\text{V}, V_{GS}=0\text{V}$	-	-	1	μA
Gate to Source Forward Leakage	$I_{GSS(F)}$	$V_{GS}=+20\text{V}, V_{DS}=0\text{V}$	-	-	100	nA
Gate to Source Reverse Leakage	$I_{GSS(R)}$	$V_{GS}=-20\text{V}, V_{DS}=0\text{V}$	-	-	-100	nA
On characteristics						
Drain to Source On-Resistance	$R_{DS(ON)}$	$V_{GS}=10\text{V}, I_D=10\text{A}$	-	9	12	$\text{m}\Omega$
		$V_{GS}=4.5\text{V}, I_D=10\text{A}$	-	14	17	$\text{m}\Omega$
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{DS}=V_{GS}, I_D=250\mu\text{A}$	1	1.45	2.5	V
Dynamic characteristics						
Gate capacitance	R_g	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1.0\text{MHz}$	-	2.0	-	Ω
Forward Transconductance	g_{fs}	$V_{DS}=10\text{V}, I_D=3\text{A}$	-	8	-	S
Input Capacitance	C_{iss}	$V_{DS}=20\text{V}, V_{GS}=0\text{V}$ $f=1.0\text{MHz}$	-	734	-	pF
Output Capacitance	C_{oss}		-	69	-	pF
Reverse Transfer Capacitance	C_{rss}		-	62	-	pF
Resistive Switching Characteristics						
Turn-on Delay Time	$t_{d(ON)}$	$V_{GS}=10\text{V}, V_{DS}=15\text{V},$ $I_D=10\text{A}, R_G=3\Omega$	-	5	-	ns
Rise Time	t_r		-	12	-	ns
Turn-off Delay Time	$t_{d(OFF)}$		-	19	-	ns
Fall Time	t_f		-	6	-	ns
Total Gate Charge	Q_g	$I_D=10\text{A}, V_{DS}=15\text{V}$ $V_{GS}=10\text{V}$	-	17	-	nC
Gate to Source Charge	Q_{gs}		-	2.8	-	nC
Gate to Drain("Miller") Charge	Q_{gd}		-	3.9	-	nC
Source-Drain Diode Characteristics						
Continuous Source Current(Body Diode)	I_S		-	-	20	A
Maximum Pulsed Current(Body Diode)	I_{SM}		-	-	80	A
Diode Forward Voltage	V_{SD}	$I_{SD}=1\text{A}, V_{GS}=0\text{V}$	-	0.75	1.2	V
Reverse Recovery Time	t_{rr}	$I_{SD}=10\text{A}, T_J=25^{\circ}\text{C}$ $dl/dt=100\text{A}/\mu\text{s}$	-	18	-	ns
Reverse Recovery Charge	Q_{rr}		-	10	-	nC

■ TYPICAL CHARACTERISTICS

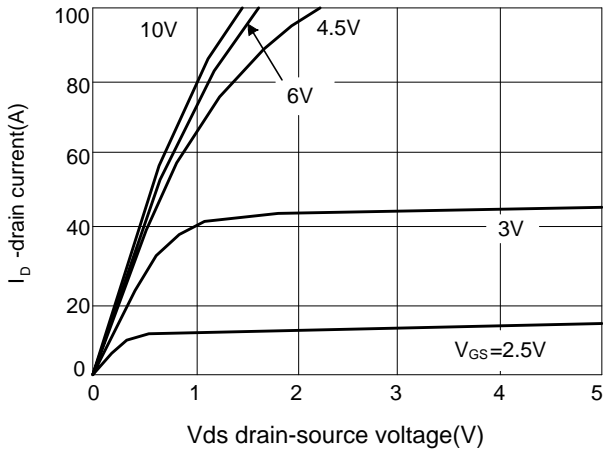


Fig.1 output characteristics

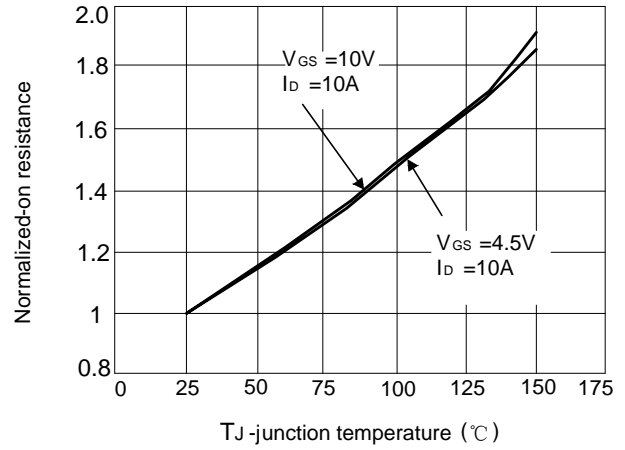


Figure.2 R_{dson} -junction temperature

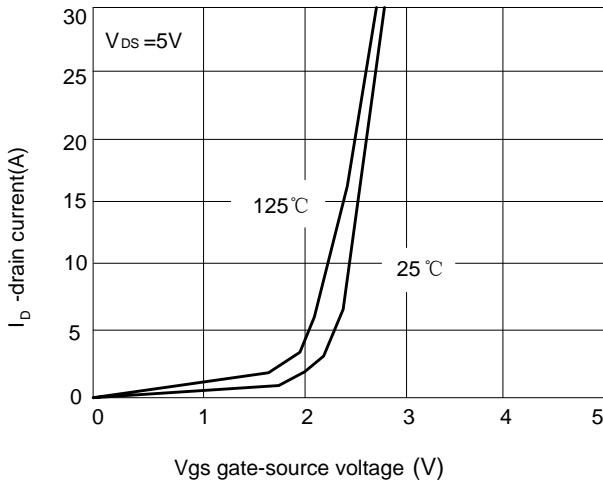


Figure.3 Transfer characteristics

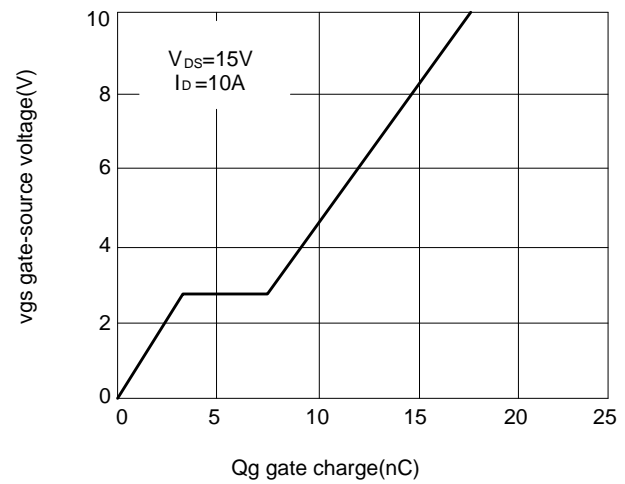


Figure.4 Gate charge

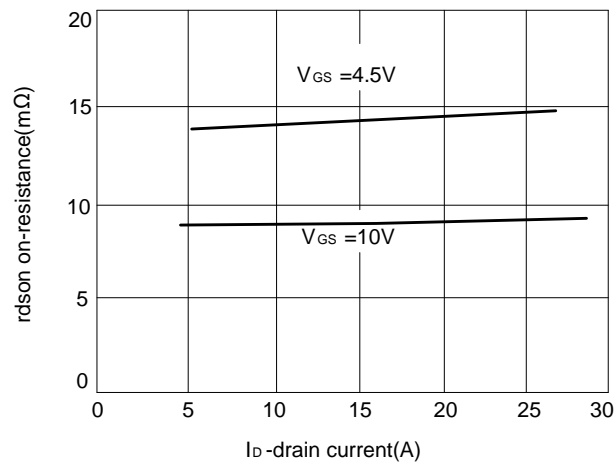


Figure.5 R_{dson} -drain current

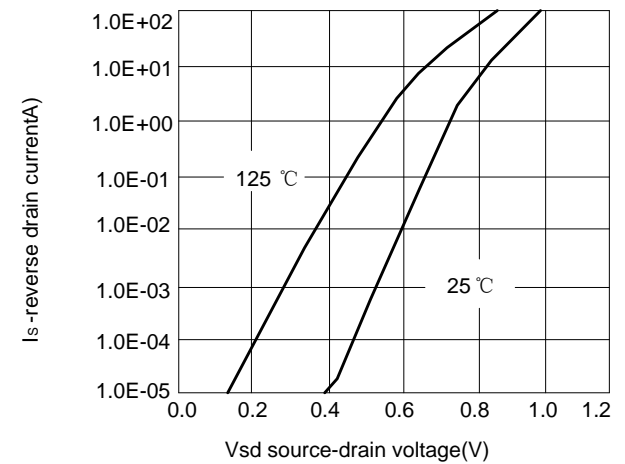


Figure.6 Source-drain diode forward

■ TYPICAL CHARACTERISTICS(Cont.)

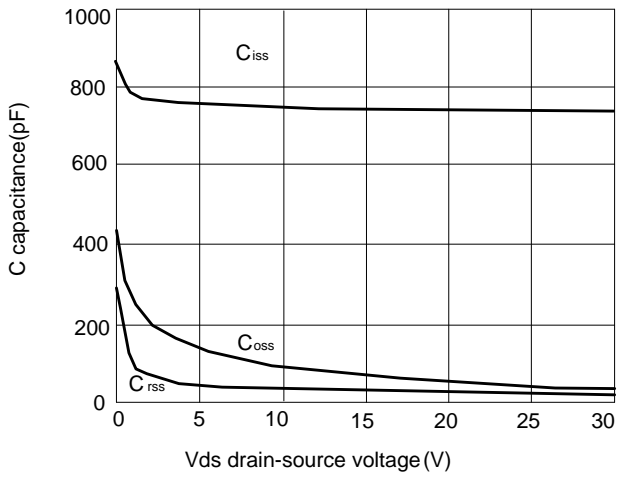


Figure.7 Capacitance vs vds

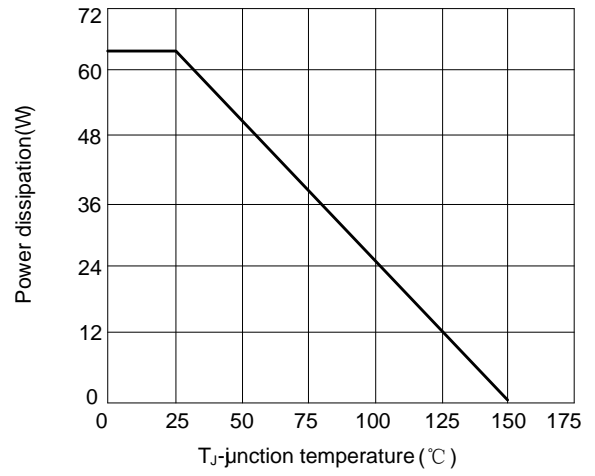


Figure.8 Power de-rating

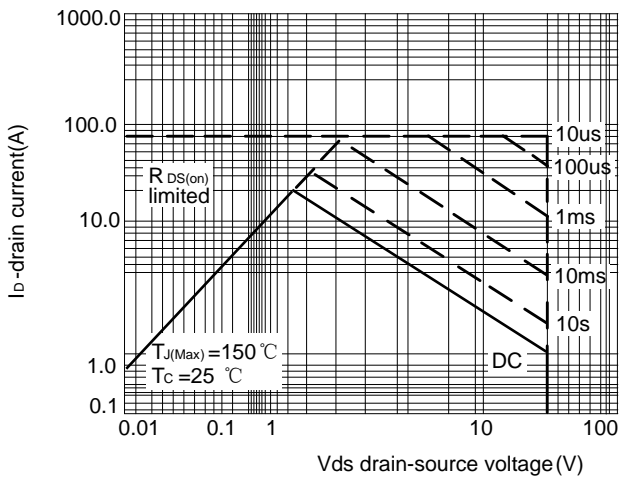


Figure.9 Safe operation area

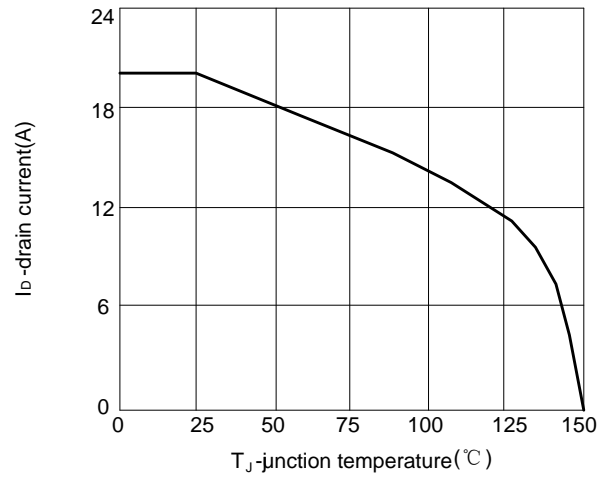


Figure.10 Id current-junction temperature

■ TO-252 PACKAGE OUTLINE DIMENSIONS

